PMEG6030EVP

60 V, 3 A Schottky barrier rectifier

20 February 2023 Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 3$ A
- Reverse voltage: $V_R \leq 60$ V
- Low forward voltage
- High power capability due to clip-bonding technology
- Small and flat lead SMD plastic package
- High temperature $T_j \leq 175$ °C
- Suitable for both reflow and wave soldering

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption application

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	δ = 0.5; f = 20 kHz; square wave; $T_{sp} \leq$ 165 °C		-	-	3	A
V_R	reverse voltage	T_j = 25 °C		-	-	60	V
V_F	forward voltage	I_F = 3 A; $t_p \leq$ 300 µs; δ ≤ 0.02; T_j = 25 °C; pulsed		-	420	475	mV
I_R	reverse current	V_R = 60 V; T_j = 25 °C; pulsed		-	115	400	µA

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 CFP5 (SOD128)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG6030EVP	CFP5	plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body	SOD128

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6030EVP	DB

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	T_j = 25 °C		-	60	V
I_F	forward current	T_{sp} = 160 °C		-	4.2	A
$I_{F(AV)}$	average forward current	δ = 0.5; f = 20 kHz; square wave; T_{amb} ≤ 95 °C	[1]	-	3	A
		δ = 0.5; f = 20 kHz; square wave; T_{sp} ≤ 165 °C		-	3	A
I_{FSM}	non-repetitive peak forward current	t_p = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	70	A
P_{tot}	total power dissipation	T_{amb} ≤ 25 °C	[2]	-	750	mW
			[3]	-	1250	mW
			[1]	-	2500	mW
T_j	junction temperature			-	175	°C
T_{amb}	ambient temperature			-55	175	°C
T_{stg}	storage temperature			-65	175	°C

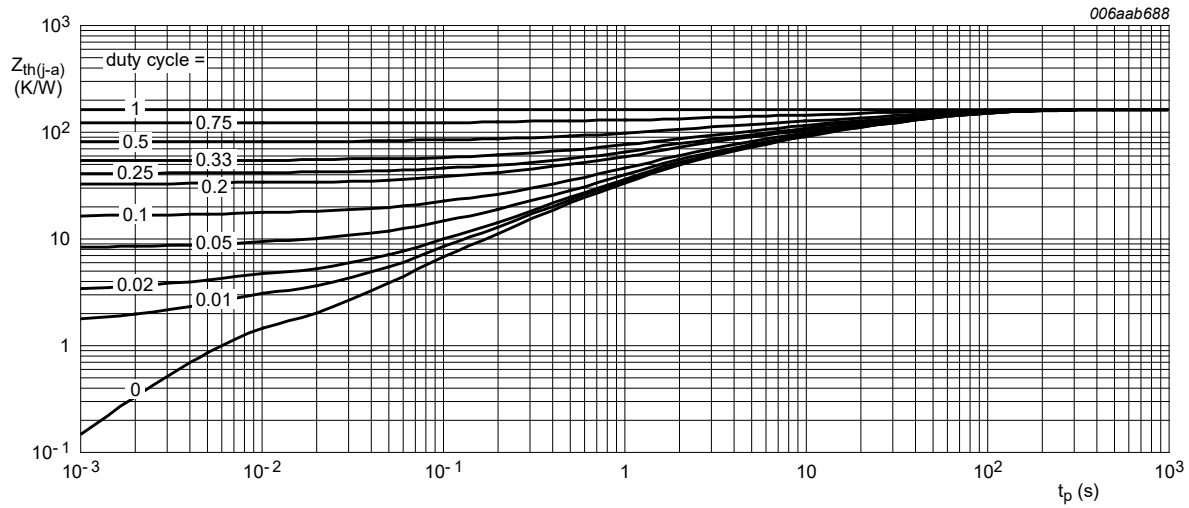
[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3, standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.

9. Thermal characteristics

Table 6. Thermal characteristics

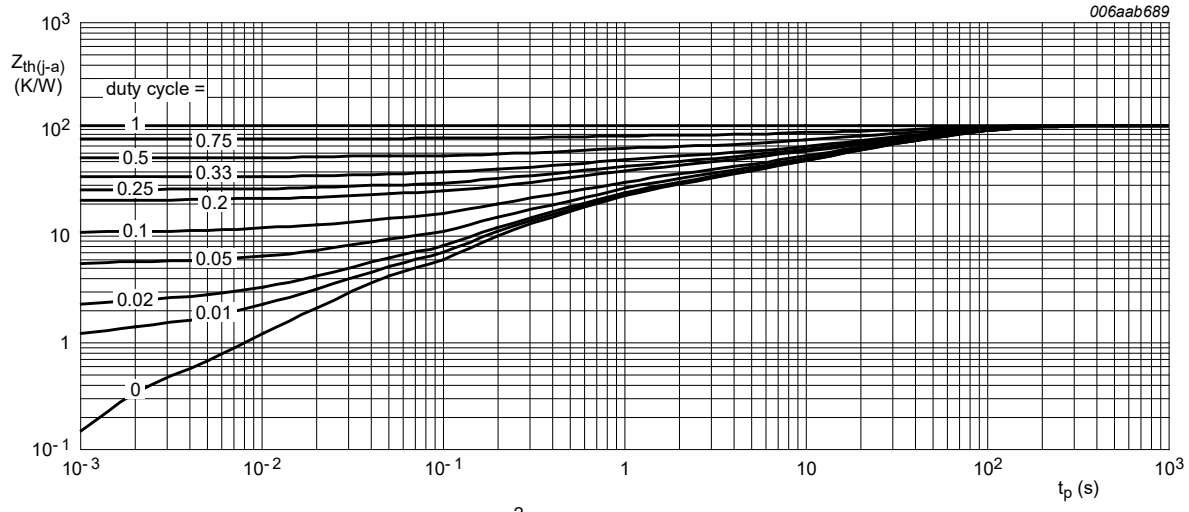
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	200	K/W
			[1] [3]	-	-	120	K/W
			[1] [4]	-	-	60	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	12	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.
[4] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.
[5] Soldering point of cathode tab.



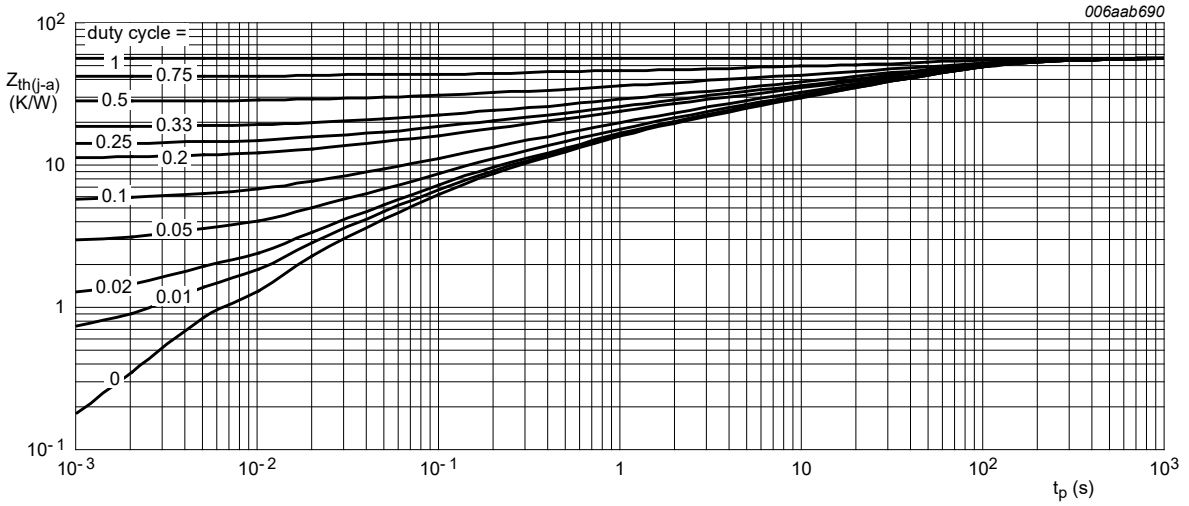
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



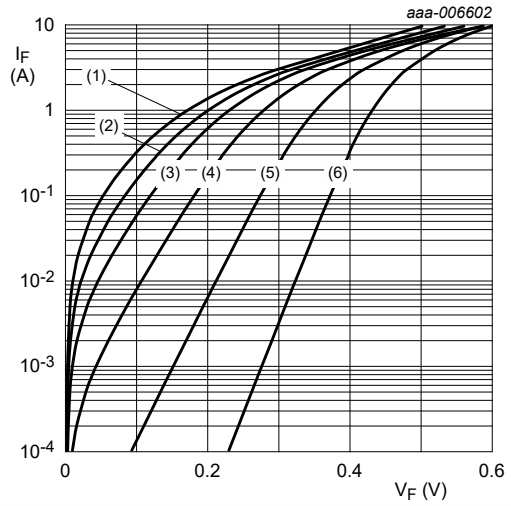
Ceramic PCB, Al_2O_3, standard footprint

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

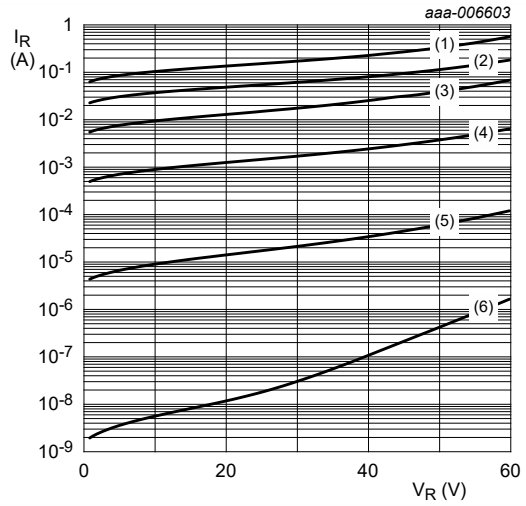
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_F	forward voltage	I_F = 0.1 A; $t_p \leq$ 300 µs; δ ≤ 0.02; T_j = 25 °C; pulsed		-	275	310	mV
		I_F = 0.5 A; $t_p \leq$ 300 µs; δ ≤ 0.02; T_j = 25 °C; pulsed		-	325	-	mV
		I_F = 1 A; $t_p \leq$ 300 µs; δ ≤ 0.02; T_j = 25 °C; pulsed		-	355	400	mV
		I_F = 1.5 A; $t_p \leq$ 300 µs; δ ≤ 0.02; T_j = 25 °C; pulsed		-	375	-	mV
		I_F = 2 A; $t_p \leq$ 300 µs; δ ≤ 0.02; T_j = 25 °C; pulsed		-	390	440	mV
		I_F = 3 A; $t_p \leq$ 300 µs; δ ≤ 0.02; T_j = 25 °C; pulsed		-	420	475	mV
I_R	reverse current	V_R = 5 V; T_j = 25 °C; pulsed		-	7	20	µA
		V_R = 10 V; T_j = 25 °C; pulsed		-	9	40	µA
		V_R = 30 V; T_j = 25 °C; pulsed		-	20	80	µA
		V_R = 60 V; T_j = 25 °C; pulsed		-	115	400	µA
		V_R = 10 V; T_j = 125 °C; pulsed		-	9	-	mA
		V_R = 60 V; T_j = 125 °C; pulsed		-	70	300	mA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz; T_j = 25 °C		-	575	-	pF
		V_R = 10 V; f = 1 MHz; T_j = 25 °C		-	200	-	pF
t_{rr}	reverse recovery time	I_F = 0.5 A; I_R = 0.5 A; $I_{R(meas)}$ = 0.1 A; T_j = 25 °C		-	20	-	ns
V_{FRM}	peak forward recovery voltage	I_F = 1 A; dI_F/dt = 40 A/µs; T_j = 25 °C		-	385	-	mV



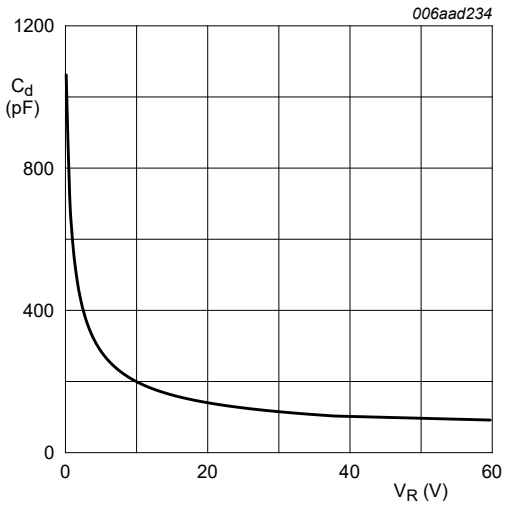
pulsed condition
(1) T_j = 175 °C
(2) T_j = 150 °C
(3) T_j = 125 °C
(4) T_j = 85 °C
(5) T_j = 25 °C
(6) T_j = −40 °C

Fig. 4. Forward current as a function of forward voltage; typical values



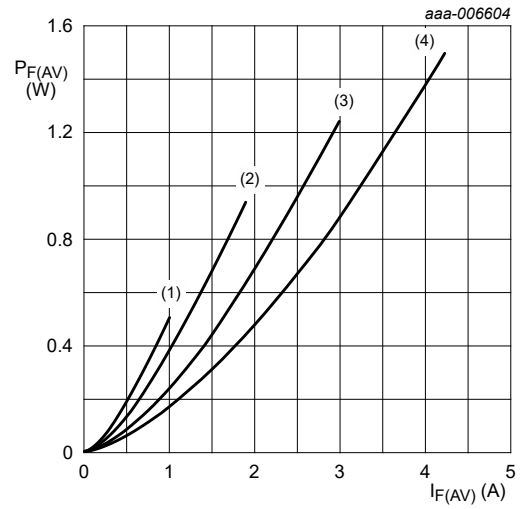
pulsed condition
(1) T_j = 175 °C
(2) T_j = 150 °C
(3) T_j = 125 °C
(4) T_j = 85 °C
(5) T_j = 25 °C
(6) T_j = −40 °C

Fig. 5. Reverse current as a function of reverse voltage; typical values



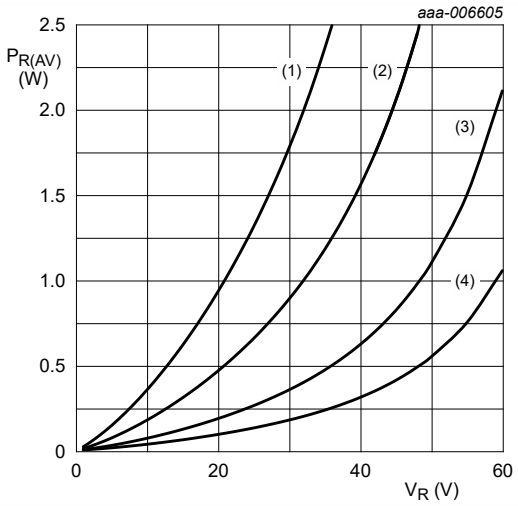
f = 1 MHz; T_{amb} = 25 °C

Fig. 6. Diode capacitance as a function of reverse voltage; typical values



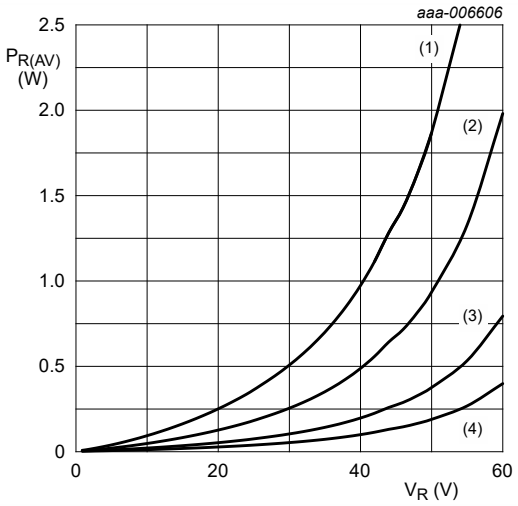
T_j = 175 °C
(1) δ = 0.1
(2) δ = 0.2
(3) δ = 0.5
(4) δ = 1

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



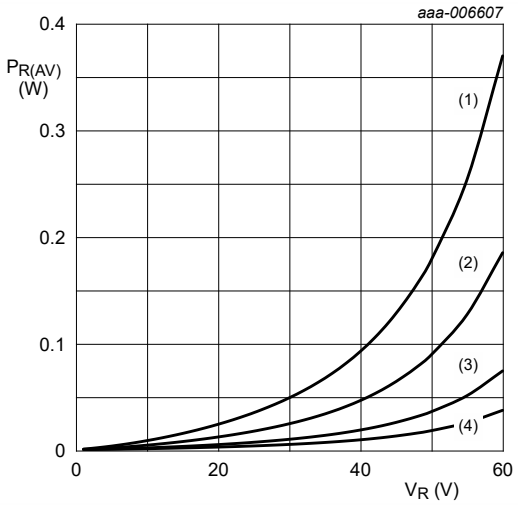
T_j = 150 °C
(1) δ = 1
(2) δ = 0.5
(3) δ = 0.2
(4) δ = 0.1

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



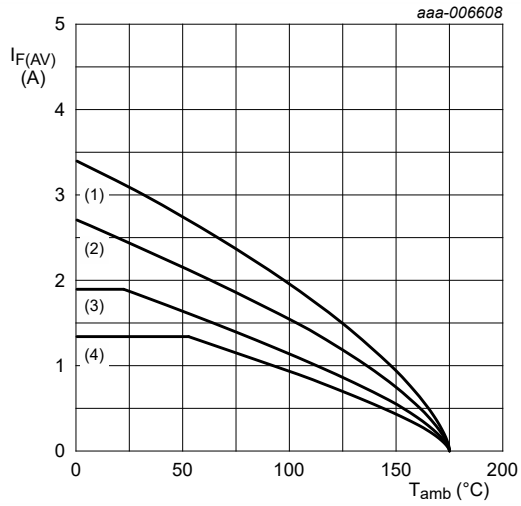
T_j = 125 °C
(1) δ = 1
(2) δ = 0.5
(3) δ = 0.2
(4) δ = 0.1

Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values



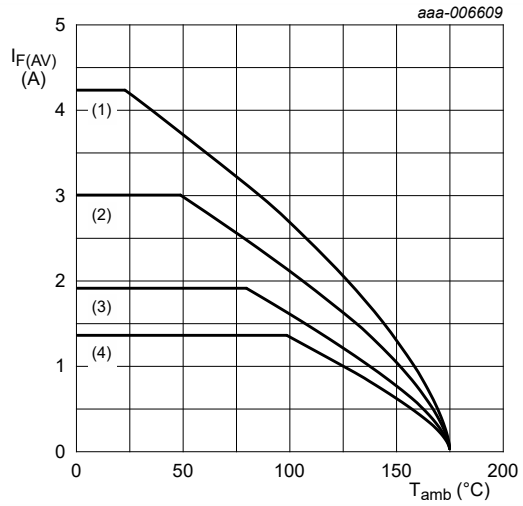
T_j = 85 °C
(1) δ = 1
(2) δ = 0.5
(3) δ = 0.2
(4) δ = 0.1

Fig. 10. Average reverse power dissipation as a function of reverse voltage; typical values



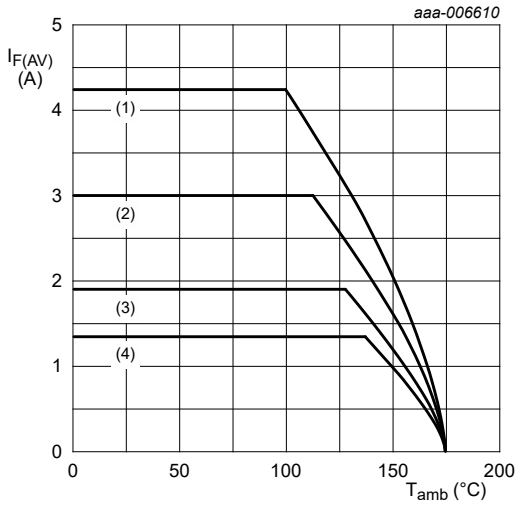
FR4 PCB, standard footprint
T_j = 175 °C
(1) δ = 1 (DC)
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



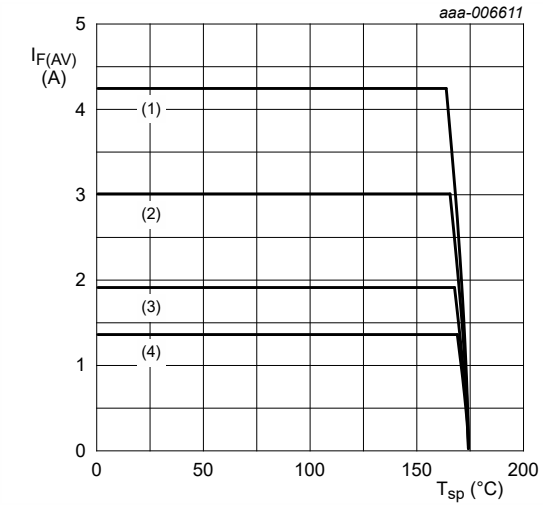
FR4 PCB, mounting pad for cathode 1 cm^2
T_j = 175 °C
(1) δ = 1 (DC)
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 12. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3, standard footprint
T_j = 175 °C
(1) δ = 1 (DC)
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 13. Average forward current as a function of ambient temperature; typical values



T_j = 175 °C
(1) δ = 1 (DC)
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 14. Average forward current as a function of solder point temperature; typical values

11. Test information

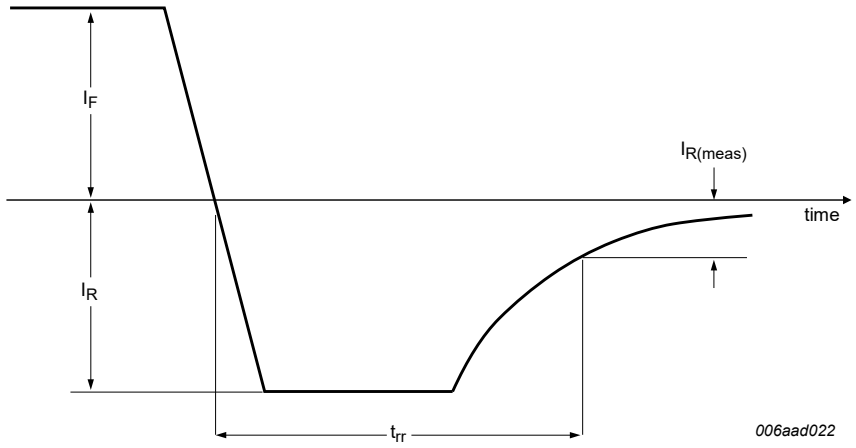


Fig. 15. Reverse recovery definition

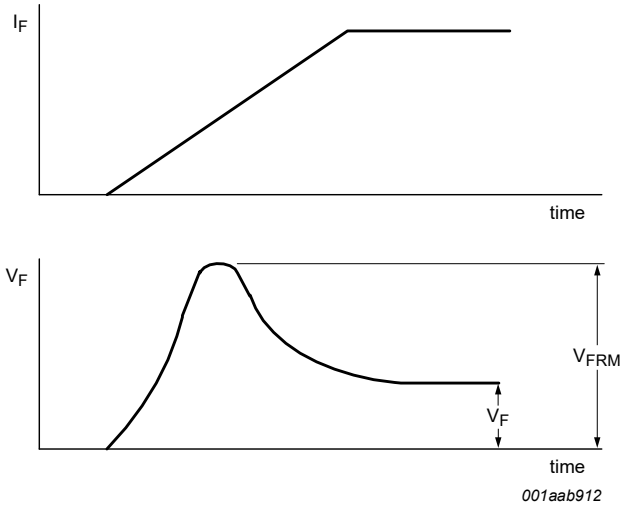


Fig. 16. Forward recovery definition

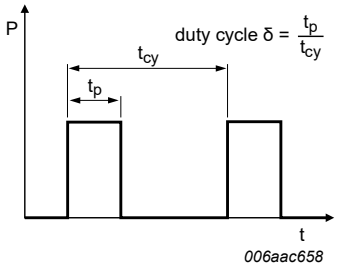


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:
$I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

$I_{RMS} = I_{F(AV)}$ at DC

$I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

12. Package outline

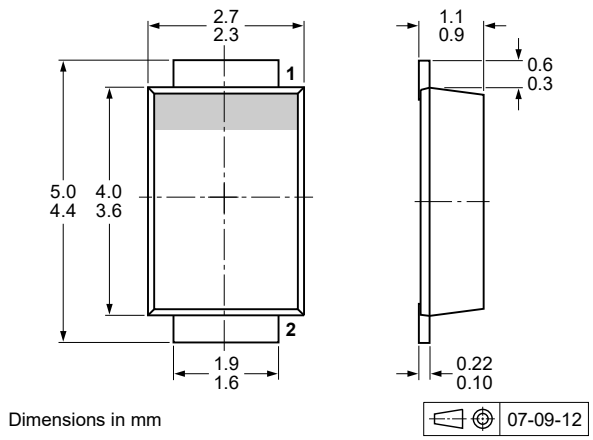


Fig. 18. Package outline CFP5 (SOD128)

13. Soldering

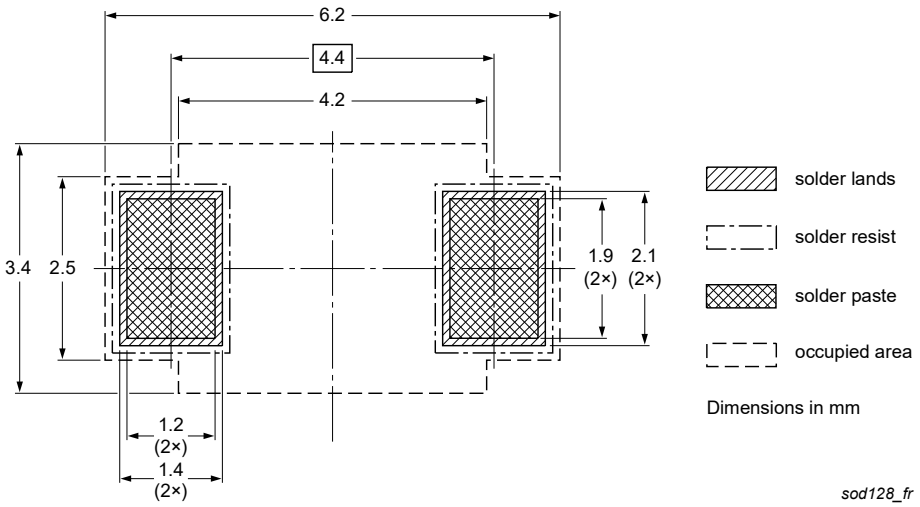
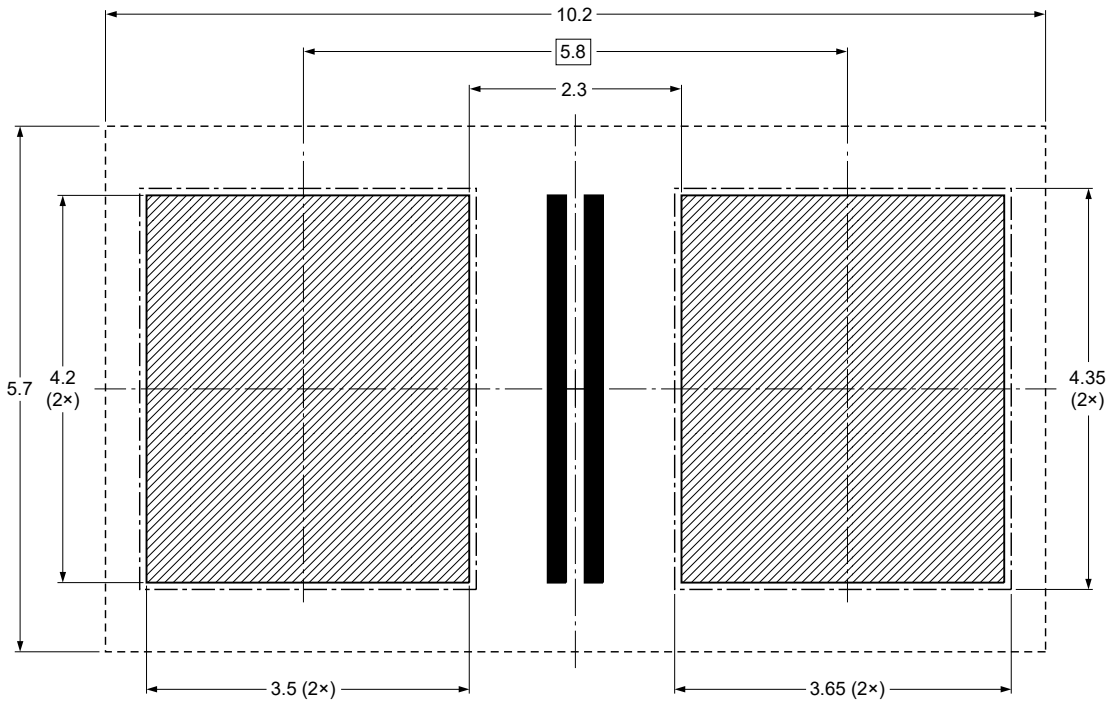


Fig. 19. Reflow soldering footprint for CFP5 (SOD128)

Wave soldering footprint information **SOD128**



occupied area

solder resist

solder lands

dummy track (solder resist and Cu free)

Dimensions in mm

Issue date ~~17-06-06~~ 17-06-07

sod128_fw

Fig. 20. Wave soldering footprint for CFP5 (SOD128)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6030EVP v.4	20230220	Product data sheet	-	PMEG6030EVP v.3
Modifications:	• Limiting values: Measurement conditions for I_{FSM} changed from square wave to half-sine wave.			
PMEG6030EVP v.3	20230101	Product data sheet	-	PMEG6030EVP v.2
PMEG6030EVP v.2	20180528	Product data sheet	-	PMEG6030EVP v.1
PMEG6030EVP v.1	20121011	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 20 February 2023

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